



Material Content Data Sheet



Sales Product Name				IPL60R385CP		Issued		25. September 2017	
MA#				MA000842334					
Package				PG-VSON-4-1		Weight*		188.27 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	5.064	2.69	2.69	26900	26900	
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		68		
	non noble metal	zinc	7440-66-6	0.051	0.03		270		
	non noble metal	iron	7439-89-6	1.017	0.54		5402		
wire	non noble metal	copper	7440-50-8	41.300	21.94	22.52	219364	225104	
	non noble metal	copper	7440-50-8	0.573	0.30	0.30	3046	3046	
	encapsulation	organic material	carbon black	1333-86-4	0.217	0.12		1152	
	plastics	epoxy resin	-	11.172	5.93		59337		
	inorganic material	silicondioxide	60676-86-0	97.074	51.57	57.62	515599	576088	
leadfinish	non noble metal	tin	7440-31-5	2.397	1.27	1.27	12734	12734	
plating	noble metal	silver	7440-22-4	0.252	0.13	0.13	1338	1338	
solder	noble metal	silver	7440-22-4	0.102	0.05		543		
	non noble metal	tin	7440-31-5	0.082	0.04		434		
	non noble metal	lead	7439-92-1	3.902	2.07	2.16	20726	21703	
heatspreader	inorganic material	phosphorus	7723-14-0	0.008	0.00		40		
	non noble metal	zinc	7440-66-6	0.030	0.02		160		
	non noble metal	iron	7439-89-6	0.601	0.32		3194		
	non noble metal	copper	7440-50-8	24.418	12.97	13.31	129693	133087	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com